## ABSTRACT

### METHOD FOR ULTRA THINNING BUMPED WAFERS FOR FLIP CHIP

In an improved method for bumped wafer thinning, a wafer is provided having a front side and a back side wherein contact pads are formed on the top surface. A dry film is formed on the front side of the wafer and openings are provided in the dry film to the contact pads. Interconnections, such as solder bumps, are formed within the openings on the contact pads. A back grind tape or carrier is attached to the dry film and overlying the interconnections. Thereafter, the wafer is thinned from the back side of the wafer.

Fig. 14